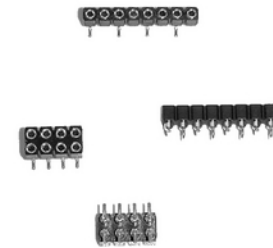


SMT-Präzisions-Buchsenleisten RM 2,54mm, stehend - BH 5,8mm SMT Precision Female Headers, 2.54mm Pitch, Vertical - 5.8mm Profile

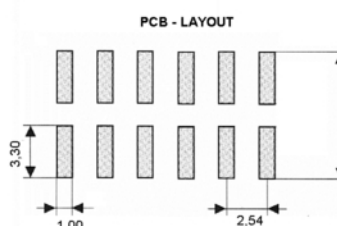
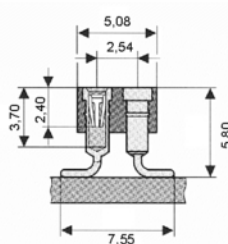
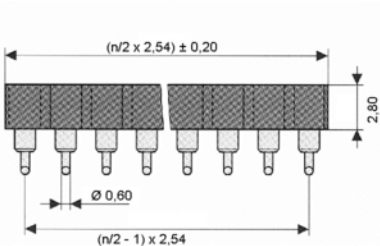
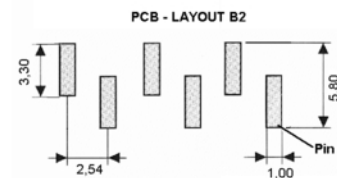
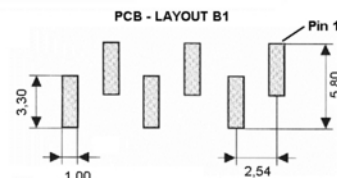
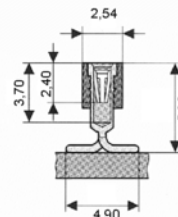
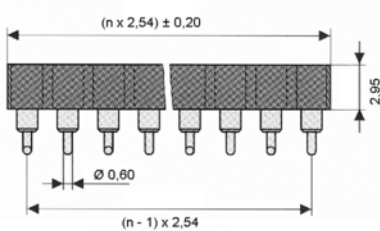
Technische Daten / Technical Data

| | |
|--|---|
| Isolierkörper <i>Insulator</i> | Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i> |
| Kontaktmaterial <i>Contact Material</i> | Hülse: Messing gedreht Feder: 6-Lamellen-Clip, Beryllium-Kupfer <i>Sleeve: screw machined brass</i> <i>Clip: 6-Finger-Clip, Beryllium-Copper</i> |
| Kontaktoberfläche <i>Contact Surface</i> | Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) <i>Acc. to options (see below), over Ni (1.3 ... 2.5µm)</i> |
| Lötbarkeit <i>Solderability</i> | IEC 60512-12A |
| Durchgangswiderstand <i>Contact Resistance</i> | < 10mΩ |
| Isolationswiderstand <i>Insulation Resistance</i> | > 1000MΩ |
| Spannungsfestigkeit <i>Test Voltage</i> | 1kV _{RMS} |
| Nennspannung <i>Voltage Rating</i> | 100V _{RMS} / 150V _{DC} |
| Nennstrom <i>Current Rating</i> | 3A |
| Temperaturbereich <i>Temperature Range</i> | -55°C ... +125°C |
| Verarbeitung <i>Processing</i> | Reflow-Lötverfahren <i>Reflow soldering</i> |



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Passende Stiftleisten Serien:
Mate with Pin Header Series:
3532/3132 3533/3133 oder 0,635mm
Vierkantstifte /
or 0.635mm square pins.



| Series | Contacts* | Rows* | Sleeve Plating | Clip Plating* | Packaging* |
|-------------|---|---|--|--|-----------------------------------|
| 1532 | 010 003-064 Einreihig <i>Single row</i> 004-072 Zweireihig <i>Double row</i> | 1 1 Einreihig B1 <i>Single row B1</i> 2 Einreihig B2 <i>Single row B2</i> 3 Zweireihig <i>Double row</i> | 50 50 Hülse verzinkt <i>Tin plated sleeve</i> | 00 00 Feder vergoldet <i>Gold plated clip</i> 10 Feder 0,25µm Gold <i>0.25µm gold plated clip</i> 30 Feder 0,75µm Gold <i>0.75µm gold plated clip</i> | PPST ST PPST PPTR |

Lieferformen / Packing Options:

ST In Stangen ohne Pick&Place-Pad / *In tubes w/o Pick&Place-Pad*
PPST In Stangen mit P&P-Pad / *In tubes with P&P-Pad*
PPTR Tape & Reel / *Tape & Reel packing*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

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FAX +49 5223 98507-50

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Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|--------------------------------------|--------------|
| Temperatur Minimum T_{Smin} | 150°C |
| Temperatur Maximum T_{Smax} | 200°C |
| Dauer $T_{Smin} - T_{Smax}$ | 60-180s |
| Temperatur Lötbereich T_L | 217°C |
| Verweildauer oberhalb T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Höchsttemperatur T_P | 260°C ±5 |
| Dauer Höchsttemperatur | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Dauer 25°C - Höchsttemperatur T_P | Max. 8 min |

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature | Key Values |
|--------------------------------------|--------------|
| Minimum Temperature T_{Smin} | 150°C |
| Maximum Temperature T_{Smax} | 200°C |
| Duration $T_{Smin} - T_{Smax}$ | 60-180s |
| Soldering Range Temperature T_L | 217°C |
| Duration above T_L | 60-180s |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3°C / s |
| Peak Temperature T_P | 260°C ±5 |
| Duration Peak Temperature | 20-40s |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6°C / s |
| Duration 25°C - Peak Temp. T_P | Max. 8min |

